

v05.0918



# GaAs HEMT MMIC LOW NOISE AMPLIFIER, 14 - 27 GHz

### Typical Applications

This HMC504LC4B is ideal for:

- · Point-to-Point Radios
- · Point-to-Multi-Point Radios
- Military & Space
- · Test Instrumentation

#### **Features**

Noise Figure: 2.2 dB @ 20 GHz

Gain: 19 dB

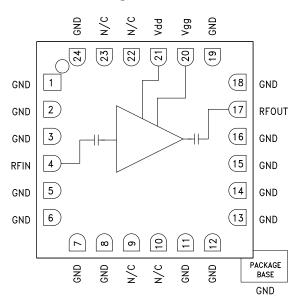
P1dB Output Power: +17 dBm Supply Voltage: +4V @ 90mA

Output IP3: +26 dBm

50 Ohm matched Input/Output

24 Lead 4x4mm SMT Package: 16mm<sup>2</sup>

### **Functional Diagram**



## **General Description**

The HMC504LC4B is a GaAs MMIC Low Noise Wideband Amplifier housed in a leadless 4x4 mm ceramic surface mount package. The amplifier operates between 14 and 27 GHz, providing up to 19 dB of small signal gain, 2.2 dB noise figure, and output IP3 of +26 dBm, while requiring only 90 mA from a +4V supply. The P1dB output power of up to +17 dBm enables the LNA to function as a LO driver for balanced, I/Q or image reject mixers. The HMC504LC4B also features I/Os that are DC blocked and internally matched to 50 Ohms, making it ideal for high capacity microwave radios or VSAT applications. This versatile LNA is also available in die form as the HMC-ALH476.

# Electrical Specifications, $T_A = +25$ °C, Vdd = +4V, Idd = 90 mA<sup>[2]</sup>

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range	14 - 20		20 - 24			24 - 27		GHz		
Gain [1]	16.5	19		16	18.5		14	17		dB
Gain Variation over Temperature		0.015			0.017			0.018		dB/°C
Noise Figure [1]		2.2	3		2.5	4.2		4.5	6	dB
Input Return Loss		15			9			7		dB
Output Return Loss		15			12			9.5		dB
Output Power for 1 dB Compression [1]		15			16.5			17		dBm
Saturated Output Power (Psat) [1]		19.5			19.5			19		dBm
Output Third Order Intercept (IP3)		24.5			25.5			26		dBm
Supply Current (Idd) (Vdd = 4V, Vgg = -0.3V Typ.)		90			90			90		mA

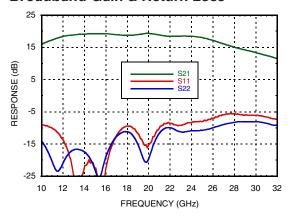
<sup>[1]</sup> Board loss subtracted out for gain, power and noise figure measurement

<sup>[2]</sup> Adjust Vgg between -1.7 to 0V to achieve Idd = 90mA

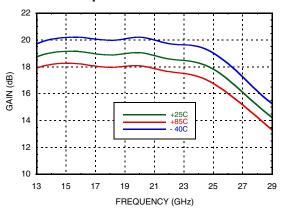




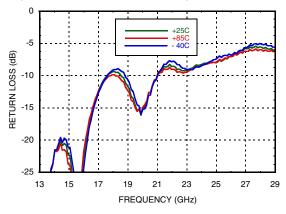
#### Broadband Gain & Return Loss [1]



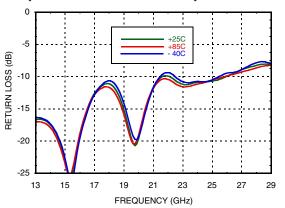
#### Gain vs. Temperature [1]



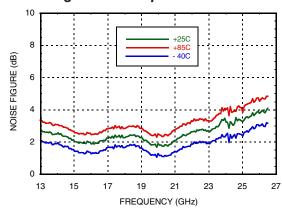
### Input Return Loss vs. Temperature



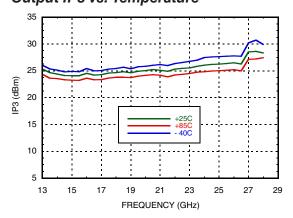
#### **Output Return Loss vs. Temperature**



### Noise Figure vs. Temperature [1]



### Output IP3 vs. Temperature

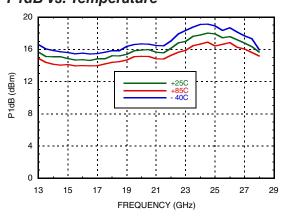


[1] Board loss subtracted out for gain, power and noise figure measurement

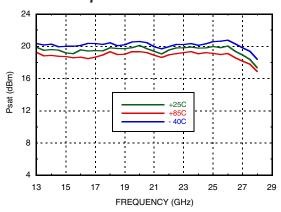




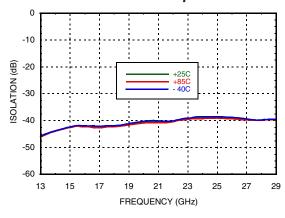
# P1dB vs. Temperature [1]



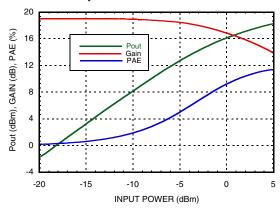
#### Psat vs. Temperature [1]



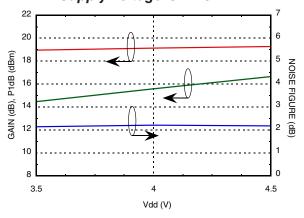
#### Reverse Isolation vs. Temperature



#### Power Compression @ 21 GHz [1]



# Gain, Noise Figure & Power vs. Supply Voltage @ 21 GHz [1]



[1] Board loss subtracted out for gain, power and noise figure measurement



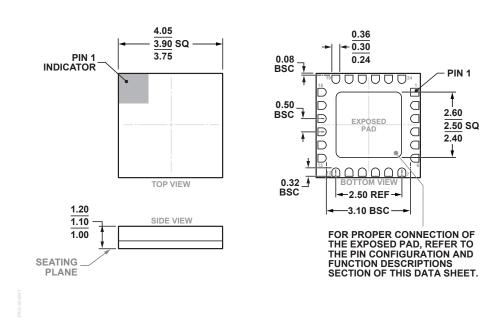


## **Absolute Maximum Ratings**

Drain Bias Voltage	+4.5V
RF Input Power	+6 dBm
Gate Bias Voltage	-2 to 0.3V
Channel Temperature	180 °C
Continuous Pdiss (T = 85 °C) (derate 20 mW/°C above 85 °C)	1.9 W
Thermal Resistance (Channel to ground paddle)	50 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A



### **Outline Drawing**



24-Terminal Ceramic Leadless Chip Carrier [LCC] (E-24-2) Dimensions shown in millimeters

# Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]	
HMC504LC4B	Alumina, White	Gold over Nickel	MSL3 [1]	H504 XXXX	

<sup>[1]</sup> Max peak reflow temperature of 260  $^{\circ}\text{C}$ 

<sup>[2] 4-</sup>Digit lot number XXXX





### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic		
1 - 3, 5 - 8, 11 - 16, 18, 19, 24	GND	Package bottom has exposed metal paddle that must be connected to RF/DC ground.	⊖ GND =		
4	RFIN	This pad is AC coupled and matched to 50 Ohms.	RFIN ○—  —		
17	RFOUT	This pad is AC coupled and matched to 50 Ohms.	—  —ORFOUT		
20	Vgg	Gate control for amplifier. Please follow "MMIC Amplifier Biasing Procedure" application note. See assembly for required external components.	Vgg o		
21	Vdd	Power Supply Voltage for the amplifier. See assembly for required external components.	Vdd 0		

# **Application Circuit**

